

IN THE CLAIMS:

Please amend the claims as follows:

1. (Previously Presented) A method of forming a semiconductor device assembly, said method comprising:
providing a substrate having an upper surface and a lower surface;
depositing a layer of copper on one surface of the upper surface and the lower surface of the substrate;
patterning the layer of copper on the one surface of the upper surface and the lower surface of the substrate to form at least one bond pad thereon;
depositing at least one layer of metal on at least a portion of the layer of copper; and
connecting one end of a conductor lead of a TAB tape to the at least one layer of metal.
2. (Previously Presented) The method of claim 1, further comprising:
connecting one end of the conductor lead of the TAB tape to the at least one layer of metal using a wire bond.
3. (Previously Presented) A method of forming a semiconductor device assembly, said method comprising:
providing a substrate having an upper surface and a lower surface;
depositing a layer of copper on the one surface of the upper surface and the lower surface of the substrate;
patterning the layer of copper on one surface of the upper surface and the lower surface of the substrate to form at least one bond pad thereon;
depositing at least one layer of gold metal on at least a portion of the layer of copper; and
connecting one end of a conductor lead of a TAB tape to the at least one layer of gold metal.

4. (Previously Presented) A method of forming a semiconductor device assembly having a substrate having an upper surface and a lower surface, said method comprising: depositing a layer of copper on one surface of the upper surface and the lower surface of the substrate; patterning the layer of copper on the one surface of the upper surface and the lower surface of the substrate to form at least one bond pad thereon; depositing at least one layer of metal on at least a portion of the layer of copper; and connecting one end of a conductor lead of a TAB tape to the at least one layer of metal.

5. (Previously Presented) The method of claim 4, further comprising: connecting one end of the conductor lead of the TAB tape to the at least one layer of metal using a wire bond.

6. (Previously Presented) A method of forming a semiconductor device assembly having a substrate having an upper surface and a lower surface, said method comprising: depositing a layer of copper on one surface of the upper surface and the lower surface of the substrate; patterning the layer of copper on the one surface of the upper surface and the lower surface of the substrate to form at least one bond pad thereon; depositing at least one layer of gold metal on at least a portion of the layer of copper; and connecting one end of a conductor lead of a TAB tape to the at least one layer of gold metal.

Please add the following new claim:

7. (New) A method of forming a semiconductor device assembly having a substrate having an upper surface and a lower surface, said method comprising: depositing a layer of copper on one surface of the upper surface and the lower surface of the substrate; patterning the layer of copper on the one surface of the upper surface and the lower surface of the substrate to form at least one bond pad thereon;

depositing at least one layer of gold metal on at least a portion of the layer of copper; and
connecting one of an end of a conductor lead of a TAB tape and a portion of a bond wire to the at
least one layer of gold metal.